

September 13–15, 2023 BIEC, Bengaluru, India

#### Messe München GmbH

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# Exhibitor application form - International Pavilion package

Company			Early Bird before 15 <sup>th</sup> March 2023			
Street, P.O. Box	ı					
City, postal code	Application deadline 30 <sup>th</sup> June 2023					
Country	I		will be allocated on first come ve basis as per space availability.			
Area code Telephone Fax		Member o	of the following trade associations:			
E-mail	· · · · · · · · · · · · · · · · · · ·	Website				
Contact: Mr. Ms. Position			GST No of your company			
☐ Manufacturer ☐ Dealer ☐ Headquarter of the parent company (address, country):	Importer	Service c	ompany (multiple entries possible)			
Under which country would you like to be included in the	e statistics:   Headquarters		Branch country:			
BILLING ADDRESS (only if address differs from above) Company		Contact				
Address	Telephone					
	 E-mail 					
Ve wish to participate and apply for the International Pavilion package:						
Price category	Price		Space request (minimum 6 m²)			
☐ Early bird (until 15 <sup>th</sup> March 2023)	EUR 345 / m² + applicable taxes		m²			
□ <b>Regular</b> (after 15 <sup>th</sup> March 2023)	EUR 381 / m² + applicable taxes		m²			

#### **International Pavilion package:**

- This offer addresses exclusively to companies, which do not have the opportunity to take part with a national pavilion and are not granted governmental support from their country.
- The International Pavilion package includes participation fee for one main exhibitor, space, shell scheme and the additional services listed in the **International Pavilion flyer** (branding, promotion and onsite services). The package prices are fixed and will not be modified. Additional orders are possible at one's own expense.

## **Important notes**

- This application form is only valid when the applicant receives a written admission confirmation from the organizer, which signifies the conclusion of the rental contract.
- The organizers cannot guarantee to comply with your demand. Space will be allocated depending on the availabilities.
- In case of cancellation, a minimum of 40% of the participation fee is payable. Please refer to clause A5 of the 'General terms of participation (A)' for more details.

## Co-exhibitors:

A charge of EUR 252/INR 18,900 plus applicable taxes will be applicable for each co-exhibitor or additionally represented company. Please fill out the form "Application for registration of co-exhibitors or represented companies" attached (page 4).

The attached Special Terms of Participation (B), the General Terms of Participation (A) and the Technical Guidelines (Bengaluru) are recognized as legally binding in all parts. Please note the cancellation conditions under A5 of General Terms of Participation (A). Each applicant acting on behalf of a third party shall be directly liable for meeting the demands of Messe Muenchen India in respect of the above trade fair.

		Company stamp & signature:
Place :	Date:	



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URL: productronica-india.com

☐ 16.8 Packaging technology

Company stamp & signature:

☐ 16.9 Complete solutions and turnkey systems for logistics



# Exhibitor application form - International Pavilion package Index of products and services (1/2)

## Important: mandatory attachment to the productronica India 2023 application form

We shall be presenting exhibits and/or services, which belong to the following product group(s) in the productronica India 2023 product index. This information is necessary for correct space allocations.

### Main product groups/clusters:

☐ 6.7 System periphery for laser-based manufacturing

Date:

If items from several main product groups are exhibited, please indicate where the emphasis lies:								
Semiconductor:		PCB & EMS:			Cables & Coils:			
	1	1 Semiconductor production □ 9		□ 9 PCB and circuit-carrier manufacturing			□ 17	Production technologies for cables and connectors
□ 2 Production of displays, LEDs and discretes □		□ 10 Electronic Manufacturing Services (EMS)			□ 18	Coilware production		
	3	Photovoltaics production	SMT:					I Production Support/Future ction – Smart Factory:
	4	Micronano production/MEMS	☐ 11 Component mount technology, pick & place			□ 19	Production materials/equipment, environmental technology	
	5	Clean-room technology	☐ 12 Soldering and joining technology for PCBs			□ 20	Services	
	6	Materials processing	□ 13	Т	est and measurement, quality assurance		□ 21	Industry 4.0
	7	Production technologies for batteries and electrical energy storage	□ 14	P	Product finishing		□ 22	Hybrid-component manufacturing
	8	Organic and printed electronics	□ 15	Р	roduction subsystems		□ 23	3D Printing, additive manufacturing
_			□ 16	P	roduction logistics and material-flow technology			
<u>Pro</u>	<u>odu</u>	ıct index (1/2): (multiple res	ponse	es	possible)			
Se	mico	nductor			7 Production technologies for batteries and	SM		
	1	Semiconductor production			electrical energy storage			omponent mount technology, pick & place
П		Wafer-front-end processing	- 1	7	.1 Materials and components for batteries and electrical			omponent preparation
		Wafer-back-end processing			energy storage			omponent mount techniques, component mounting
		Production of power electronics (IGBT, Power	1	7	.2 Equipment for batteries and electrical energy storage		11.3 Pr	oduction
	1.5	MOSFET, Thyristors, etc.)	1	7	.3 Inspection and test systems for batteries and			andling technology
п	1 /	Measurement, detection and control systems for			electrical energy storage		12 Sc	oldering and joining technology for PCBs
	1.4	semiconductor production		7	.4 Accumulators		12.1 Sc	olders and soldering aids
	15	Packaging and assembly materials		8			12.2 Pa	aste application systems and stencils
		Electronic components		□ 8	.1 Materials and components		12.3 Sc	oldering units
			l l	B	.2 Manufacturing equipment		12.4 Sc	oldering equipment
2 Production of displays, LEDs and discretes		Electronic applications			.2 Manufacturing equipment 3 Inspection and test systems			•
	2	Production of displays, LEDs and discretes		□ 8	.3 Inspection and test systems		12.5 Sc	oldering accessories
	<b>2</b> 2.1	<b>Production of displays, LEDs and discretes</b> Display manufacturing		□ 8			12.5 Sc 12.6 G	oldering accessories luing, dispensing, varnishing, coating
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September 13–15, 2023 BIEC, Bengaluru, India

#### Messe München GmbH

Messegelände 81823 Munich, Germany Tel.: +49 89 949-20322 Fax: +49 89 949-97 20322

E-mail: info@productronica-india.com URL: productronica-india.com



# Exhibitor application form – International Pavilion package Index of products and services (2/2)

## Important: mandatory attachment to the productronica India 2023 application form

Product index (2/2): (multiple responses possible)

Cables & Coils  17 Production technologies for cables a connectors  17.1 Cable and wire processing  17.2 Tools for wiring  17.3 Cable-processing equipment  17.4 Others  17.5 Cable-protection devices  17.6 Processing equipment for cable-protect  17.7 Technology for detachable connections  18 Coilware production  18.1 Materials for coilware  18.2 Production equipment for coilware  18.3 Applications for coilware	19 Production materials/e technology  19.1 Preliminary products and 19.2 Preliminary products and metallic  19.3 Process materials ion devices  19.4 Plant equipment	21.1 Autonomous interconnected micro systems, sensor and actuator networks, cyber physical systems     21.2 Software: basic systems and development tools     21.3 Machine software     21.4 Manufacturing software     21.5 Business software     21.6 Software services     21.7 Application specific software     22.1 Tooling and mouldmaking     22.2 Tools, tool equipment     22.3 Assembly and handling technology, periphery     22.4 Stamping     22.5 Shaping     22.5 Shaping     22.6 Software services     22.7 Software services     23.6 Software services     24.7 Application specific software     25.8 Shaping     26.8 Software services     27.8 Software services     28.8 Software services     29.9 Software services     29.9 Software services     20.9 Software services     21.7 Application specific software     22.8 Software services     23.8 Software services     24.9 Software services     25.8 Software services     26.8 Software services     27.8 Software services     27.9 Software			
		□ 23.3 Materials			
□ Aviation and aerospace □ □ Consumer electronics □ □ Electrical engineering □ □ Energy technology □ □ Home entertainment □ □ Industrial □ □  Top 5-Target companies Please indicate here, which co	LED/lighting manufacturing Measuring, control and automation te Mechanical engineering/apparatus pr Medical Military and defense Office and data processing technolog Other manufacturing industry	roduction  Semiconductor manufacturing  Service sector  Telecommunications  gy (OEM)  Trade (specialized retail, retail, distribution)			
Target department/s Please indicate here, which is/a	are your target department/s (sou	urcing, design etc.):			
We are also interested in					
□ productronica, Munich, Germany (productronica.com)					
□ productronica, Municri, Germany (productronica.com) □ productronica China, Shanghai (productronica-china.com)					
Place : Da	nte:	Company stamp & signature:			



September 13-15, 2023 BIEC, Bengaluru, India

Messe München GmbH

Messegelände 81823 Munich, Germany
Tel.: +49 89 949-20322
Fax: +49 89 949-97 20322
E-mail: info@productronica-india.com



URL: productronica-india.com

# Co-exhibitor/additionally represented company Exhibitor application form - International Pavilion package

(to be filled in by the main exhibitor)

STAND NO. (if already known	)	COMPANY		
Mobile	E-mail	Tel.		
We hereby authorize the com and commercial documents no The exhibits correspond with the CO-EXHIBITOR	ecessary for the information of the "Index of products and so	visitors concerning the	e exhibits or ica India 20	23.
Company			I	
Street, P.O. Box			.l 	
City, postal code			.ı _[	
Country			 .l	
Area code Telephone  Length E-mail	Fax		_     Website	
E-maii			Website	
Contact: ☐ Mr. ☐ Ms.	Position			epresentative (president, chairman, manager, etc.)
☐ Manufacturer ☐	Dealer	☐ Distributor ☐	Service	company (multiple entries possib
Headquarter of the parent compan Under which country would you like			rs 🗆	Branch country:
INDEX OF PRODUCTS	AND SERVICES			
Semiconductor Cluster  Semiconductor production  Production of displays, LEDs and discretes  Photovoltaics production  Micronano production/MEMS  Clean-room technology	□ PCB & EMS Cluster □ PCB and circuit-carrier manufacturing □ Electronic Manufacturing □ Services (EMS)	☐ Test and measurer quality assurance ☐ Product finishing ☐ Production subsys ☐ Production logistic material-flow techn	tems s and	□ Overall Production Suppor Future Production – Smart Factory □ Production materials/equipment environmental technology □ Services
Materials processing Production technologies for patteries and electrical energy storage Organic and printed electronics	□ SMT Cluster □ Component mount technology, pick & place □ Soldering and joining technology for PCBs	□ Cables & Coils □ Production technol cables and connect □ Coilware production	ogies for tors	<ul> <li>☐ Industry 4.0</li> <li>☐ Hybrid-component manufacturin</li> <li>☐ 3D Printing, additive manufacturing</li> </ul>
The participation fee for each ac and will be charged to the main e exhibition badges.				<b>52/INR 18,900</b> + applicable taxes the show directories and free
		Company star	np & signati	ure:
lace ·	to:			

Venue: Bangalore International Exhibition Centre (BIEC), Bengaluru India

Duration and opening hours: September 13-15, 2023; 10:00-18:00

Messe München GmbH (Messe München) Messegelände, 81823 Munich, Germany

Tel.: +49 89 949-20322 Fax: +49 89 949-97 20322

Email: info@productronica-india.com URL: productronica-india.com Organizer: Messe Muenchen India

## **Special Terms of Participation (B)**

All prices indicated below are net and are subject to Indian taxes, which shall be borne by the exhibitor. There might be further tax requirements in the exhibitor's state of residence; these taxes shall be borne by the exhibitor as well.

#### B1. Application(see A1)

Applications are to be made online, which should be submitted to Messe Muenchen India at the earliest opportunity, Terms and conditions applies to all applicants who have completed and submitted their application online.

#### B 2. Permitted exhibits and exhibitors (see A2)

All domestic and foreign manufacturers or their Indian subsidiaries, general importers and specialist dealers authorized by the manufacturers are admitted as exhibitors. General importers and authorized specialist dealers may only exhibit machines and plants whose manufacturers are not represented at the exhibition.

All exhibits must correspond to the relevant range of exhibits for this trade fair and be designated by name and category on the application form. Articles other than those permitted and registered, as well as used or leased machinery, may not be exhibited. Messe Muenchen India has the

#### B 3. Co-exhibitors and additionally represented companies (see A1/2/4)

Permission for co-exhibitors and additionally represented companies must be requested in writing. The registration fee is EUR 252/INR18,900 + applicable taxes for each coexhibitor or additionally represented company admitted

#### B 4. Participation fees (see A7)

The International Pavilion package includes participation fee for one main exhibitor, space, shell scheme and the additional services listed in the International Pavilion flyer (branding, promotion and onsite services). Please see separate flyer for details. The package prices are fixed and will not be modified. Additional orders are possible at one's own expense. The minimum stand size is 6 square meters. The package price per square meter is:

- Early Bird (before March 15, 2023): EUR 345/m² + applicable taxes

- Regular (after March 15, 2023): EUR 381/m² + applicable taxes

Besides the booking of the International Pavilion package, the participation fees include extensive services provided by Messe Muenchen India, such as consultation and planning advice, publicity work, organization and technical assistance.

#### B 5. Terms of payment (see A7)

The deadlines for payment given in the invoices must be observed. This application form is only valid when the applicant receives a written admission confirmation from the organizer, which signifies the conclusion of the rental contract.

Each square meter or part thereof will be included in full in the calculation, the floor area always being considered rectangular, without taking account of projections, supports, service connections and the like. The applicant shall be invoiced for 100% of the projected participation price shortly after receiving his written admission confirmation. This payment will be refunded if the applicant is not admitted to the trade fair, but will be forfeited if unilaterally the applicant withdraws totally from the undertaking.

Payment of the invoices is due immediately unless other payment deadlines are stated in the invoices. Payment of the participation price as well as payment for admitting co-exhibitors is a prerequisite for occupation of the exhibition area. Prior payment in full of the amount invoiced is a condition for access to the exhibition area, an entry in the catalog, and provision of workers' and exhibitors 'passes.

The applicant or exhibitor will receive invoices for all additional charges (e.g., technical services, advertising material) with the confirmation of the order; they are to be paid immediately on receipt.

All invoiced amounts in all Messe Muenchen India invoices, related to the event, are to be paid in INR/EUR, without deductions and free of all charges, by credit transfer to the account specified in the invoices, mentioning the exhibitor's company name and invoice number. If any deductions or withholdings are required to be made under applicable law, the amount payable to Messe Muenchen India shall be grossed up such that the amount actually paid to Messe Muenchen India shall be no less than the amount of the invoice.

#### B 6. Dates of setting up and dismantling (see A14)

- Set-up day: September 12, 2023 from 12:00-20:00
- Show days: September 13–15, 2023 from 10:00-18:00 Dismantling must be completed by 23:59 on September 15, 2023

An extension is possible only in exceptional cases and entirely at the discretion of Messe Muenchen India. No permission for extension shall be deemed to have been provided unless it is in writing from the Messe Muenchen India's Operations Department.

#### B 7. Stand design and equipment (see Technical Guidelines)

Stand height: The maximum construction and advertising height for stand construction is five (5) meters.

Stand open sides: In order to preserve the character of trade show as a communication and business trade show, exhibitors are requested to ensure an open stand design. Messe Muenchen India is entitled to demand changes in the exhibition stand design in this context. Stand designs can only be approved if the open sides of the booth have a uniformly open design. Erecting closed walls is permitted, provided they do not take up more than 30% of the total length of the respective stand open side, and closed walls may be no more than six (6) meters in length. A closed length of wall measuring six (6) meters must be followed by an opening at least two (2) meters wide. Messe Muenchen India reserves the right to allow exceptions to this ruling in individual. Assuming that the Technical Guidelines are observed in designing and constructing a stand, drawings need to be submitted for one-story stand construction in the halls insofar as they are built by the exhibitor. On request, Messe Muenchen India will check submitted stand construction plans (submitted in two copies) for exhibitors. No specific approval will be issued.

All other stand constructions which are higher than three (3) meters (multi- story stands, mobile stands, stands with bridges, stairs, cantilevered roofs, galleries, etc.) and constructions on the open-air exhibition grounds require written approval from Messe Muenchen India.

Two-story stand construction is permitted in the halls with the approval of a top-level certified structural engineer, who is employed by the exhibitor or recommended by Messe Muenchen India. Approval for the two-stories stand depends on the position of the stand within the hall and the area it occupies. Stand drawings containing elevations and cross-sections, cutaway view, electricity layout, static test report or static load calculation, specification of construction must be submitted in duplicate to Messe Muenchen India's Operations Department for approval by the deadline specified, at the latest eight (8) weeks before stand assembly is to start.

For two-story structure covering more than 30 square meters, exhibitors need to install sprinkler system on the ceilings of each story. The structures of the stand cannot hang on the structures of the hall. It must be attached to the hall structure. In the case of the structures of the hall. It must be attached to the hall structure. In the case of infringement of any of the conditions specified here, Messe Muenchen India is entitled to act in accordance with the General Terms of Participation. Messe Muenchen India will erect partition walls only upon request and at the exhibitor's expense. Exhibitors will receive, in good time, the order form for these walls and further stand walls (height 2.50 meters) with the Online Exhibitor Manual.

#### B 8. Other regulations

All building structures on the trade fair grounds shall be executed in accordance with the legal requirements for construction materials. Revolving tower cranes, etc. must be secured according to regulations. Suspending advertising media or other loads (apart from flags) from cranes is prohibited for safety reasons.

#### B 9. Technical installations

Applications for electrical installation, water, drainage, and telecommunications can be considered only if submitted in due time on the order forms available from Messe Muenchen India. The precise terms of delivery and the connection fees are stated on

#### B 10. Restoration of the exhibition areas

All exhibition areas must be handed over to Messe Muenchen India's Operations Department in their original condition by the stipulated date for completion of dismantling. At the end of the exhibition, exhibitors must remove from the site all the materials especially the double-sided carpet tape used from their stands by the respective timings stated in the "Operations Schedule".

Messe Muenchen India is entitled to charge the exhibitor concerned for the removal of excessive waste (stand construction debris, crates/pallets, cartons, packing materials or literature) by a contracting firm at exhibitor's cost. Such costs shall be paid immediately to Messe Muenchen India by the exhibitor upon receipt of the charges from Messe Muenchen India.

#### B 11. Use of equipment

Only cranes, fork-lift trucks and working platforms may be used that have been provided by the Messe Muenchen India service partners responsible. In special cases, the consent of Messe Muenchen India's Operations Department is required

#### B 12. Transport of track-laving vehicles

Only track-laying vehicles with smooth track plates that are also approved for public roadways, may be driven on the roads of the trade fair grounds. The transport of tracklaying vehicles into the exhibition halls is permitted only with the express approval of Messe Muenchen India's Operations Department. The exhibitor is fully responsible for any damage to road surfaces and hall floors.

#### B 13. Sales regulations

Direct sales and other services or deliveries made from the stand are not permitted. Exhibited goods must not be delivered to purchasers until after the trade fair closes. Sales are permitted only to wholesalers, retail or trade customers.

#### B 14. Catalog, website, visitor information

An online show catalog will be compiled for the trade fair. All exhibitors (including co-exhibitors, companies at joint stands and additionally represented companies) are included, with the name indicated in the application, in the alphabetical list of exhibitors in these media. The minimum entry contains the exhibitor's company name, hall and stand number in the alphabetical list of exhibitors.

Exhibitors (including co-exhibitors and companies at joint stands) will be offered other entries, e.g., in the "product index", and other forms of presentation in these media on a separate order form. The forms will be sent to applicants in good time.

Messe Muenchen India assumes no responsibility for the correctness and completeness of the online catalog. The exhibitor is solely responsible for the permissibility under law—and particularly the law on competition—of any advertisement placed in the trade fair catalog. Should third parties assert claims against Messe Muenchen India on account of the impermissibility of the advertisement under law in general or the law on competition, the advertiser shall hold Messe Muenchen India fully safeguarded against all claims asserted including all costs of any necessary defense in court on the part of Messe Muenchen India. The same applies to exhibitor entries actuated by exhibitors in the trade fair catalog, the online database or the visitor information of Messe Muenchen

#### B 15. Exhibitors' and workers' passes (see A13)

For the time in which the trade fair is held, each exhibitor receives the following number of exhibitors' passes free of charge:

Space	Passes	Space	Passes
12-17 m²	5	55–100 m²	30
18-26 m²	10	101–400 m²	40
27-54 m²	20	over 400 m <sup>2</sup>	maximum 50

The number of exhibitor's passes is not increased for co-exhibitors or additionally represented organizations. Additional exhibitors' passes are obtainable from the trade fair management. Exhibitors' passes are intended solely for stand personnel and must not be passed on to third parties.

Workers' passes for setting up and dismantling of stands are available in the numbers required. These passes are valid only during the time of setting up and dismantling and do not authorize the holder to enter the trade fair center during the event. Workers' passes must not be passed on to unauthorized third parties, i.e., to any third party not in a relationship of permanent or temporary employment with the exhibitor

#### B 16. Circular

Once the stands have been allocated, exhibitors will be informed by circular of further details concerning preparation and organization of the trade fair.

#### B 17. Alterations

Messe Muenchen India reserves the right to make alterations and additions in matters affecting technical arrangements and safety.

## **General Terms of Participation (A) TECHNICAL GUIDELINES** (Bengaluru)

All potential exhibitors wishing to take part in the event must express their wish to do so by fully completing and submitting the application form to Messe Muenchen India. With the application, exhibitors express to Messe Muenchen India their serious interest in taking part in the event as exhibitors. All exhibits must be described precisely on the application form. Co-exhibitors and additionally represented companies must be named on the application form. The same particulars must be specified as for the exhibitor. Incomplete applications cannot be considered.

A 2. Eligible exhibits and exhibitors
The Special Terms of Participation (B), the General Terms of Participation (A), as well as the Technical Guidelines (Bengaluru) are accepted as legally binding with submission of application documents. The application of the exhibitor represents the contractual offer. The admission or rejection will be confirmed to the exhibitor in writing in due time. Admission cannot be transferred.

The contract between Messe Muenchen India and the exhibitor is concluded with the admission. According to this contract, Messe Muenchen India is authorized to assign a stand area to an exhibitor, which might deviate from the information in the application form unless these deviations are unacceptable for the exhibitor. A deviation is considered acceptable if Messe Muenchen India does not receive the exhibitor's rejection of the assignment of the stand area within one week. If an exhibitor rejects a stand area before the deadline and the assigned stand area is unacceptable for the exhibitor, the exhibitor can demand that Messe Muenchen India assign him an acceptable stand area. If Messe Muenchen India does not comply with the demand within an appropriate time period, the exhibitor can withdraw from the contract. The exhibitor does not have any more far-reaching

Exhibitors do not have a legal claim to admission unless such a claim results from the law. Exhibitors who have not fulfilled their financial obligations to Messe Muenchen India, e.g., in respect of previous events, or have infringed the regulations governing the use of the event

grounds, or the terms of participation, may be excluded from admission.

Messe Muenchen India is entitled to withdraw from the contract or to terminate the contractual relationship forthwith without notice if admission was based on incorrect or incomplete statements by the exhibitor, or if, later, the exhibitor no longer fulfils the conditions for admission. Only declared and admitted articles shall be exhibited. Messe Muenchen India has the right to remove any other exhibits at the exhibitor's risk and expense.

Hired or leased articles shall not be exhibited. Messe Muenchen India is entitled to remove such objects at the exhibitor's risk and expense. An exception is made in the case of objects which are not part of the exhibitor's range of goods, but which are required for their display

(e.g., for demonstration purposes).

Co-exhibitors shall not be admitted, nor additional organizations represented, unles expressly specified in the notice of admission.

Messe Muenchen India may exclude specific exhibition objects from the admission and link the admission with conditions. The exhibitor's reservations, conditions, and particular wishes (e.g., regarding location, exclusion of competitors, stand construction or design) will be considered only if expressly confirmed in the notice of admission. Space will be allocated according to Messe Muenchen India's requirements and the prevailing conditions, and in accordance with the classification system for the trade fair as applied by Messe Muenchen India at its own discretion, and not according to the order in which applications are received.

The application of the exhibitor represents the contractual offer. The admission or rejection will be confirmed to the exhibitor in writing in due time. Admission cannot be transferred. The rental contract comes into force when the organizer has notified the exhibitor in writing that he is admitted. This generally occurs when the booth location has been confirmed by both sides. According to this contract, the organizer is authorized to assign a stand area to an exhibitor, which might deviate from the information in the application unless these deviations are unacceptable for the exhibitor. A deviation is considered acceptable if the organizer does not receive the exhibitor's rejection of the assignment of the stand area within one week.

The allocation of the other stands, in particular of neighboring stands, can change by the time the trade fair opens. Messe Muenchen India is also entitled to relocate or close entrances to and exits from the trade fair grounds and halls, and to make other structural alterations. Exhibitors cannot make claims against Messe Muenchen India because of such

Messe Muenchen India may also subsequently, i.e., after the rental contract and the stand assignment have come into force, change space allocations, and in particular change the location, type, dimensions and size of the exhibition area rented by the exhibitor, insofar as this is necessary for reasons of safety or public order, or because the trade fair is oversubscribed and further exhibitors must be admitted or because changes in assignments of exhibition space ensure that the facilities and space required for the trade fair are used more efficiently. However, such subsequent changes may not exceed the scope which the exhibitor can reasonably be expected to accept. Should such subsequent changes result in a lower participation fee, the difference in amount will be refunded to the exhibitor. Further claims against Messe Muenchen India are excluded.

If exhibitors cannot use their stand space or are impaired in the use of their stand because

they have infringed legal or official regulations or the Terms of Participation A and B or the Technical Guidelines, they are nevertheless obliged to pay the participation fee in full and to pay Messe Muenchen India compensation for all damage caused by themselves, their legal representatives or employees; exhibitors are not entitled to cancel or terminate the contract unless the law specifically entitles them to do so.

#### A 4. Co-exhibitors and additionally represented companies

A co-exhibitor is one who presents his own goods or services, using his own staff, at the stand of another exhibitor (the main exhibitor). This definition includes group companies and subsidiaries. Agents and representatives are not admitted as co-exhibitors. In the case of an exhibitor who is also a manufacturer, an additionally represented company is any other company whose goods or services are offered by the exhibitor.

If an exhibitor who is a distributor displays not only the products of one manufacturer but also goods and services of other companies, then this count as additionally represented companies. Admission of the exhibitor does not mean that a contract exists between Messe Muenchen India and the co-exhibitors or other companies he represents. Co-exhibitors are admitted against payment. This also applies to additionally represented companies if specified in the Special Terms of Participation B. The exhibitor must make this

payment. The amount can also be invoiced subsequently by Messe Muenchen India. The exhibitor is responsible for ensuring that his co-exhibitors and other companies he represents comply with the Terms of Participation A and B, the Technical Guidelines as well as the instructions of the Trade Fair Management. The exhibitor is liable for the debts and negligence of his co-exhibitors or additionally represented companies as if they were his own. If co-exhibitors make direct use of Messe Muenchen India services by submitting the required application form, Messe Muenchen India is entitled to invoice the exhibitor for these services. He is jointly and severally in whole to third parties, without Messe Muenchen India's prior written consent. This application procedure does not apply to organizers of joint stands. They are not exhibitors as defined by the Terms of Participation.

For the avoidance of doubt, it is clarified that Messe München is merely acting as a collection agent of Messe Muenchen India and is deemed to be an agent of Messe Muenchen India for the purposes of this agreement including for the purposes of the Arbitration provisions at Clause A (19).

#### A 5. Cancelling the contract

Messe Muenchen India reserves the right to make changes to location, type, dimensions or size of the exhibition area rented by the exhibitor depending upon the venue owner, final layout plans, utility services plan and keeping in mind the security and safety of the venue premises. The exhibitor shall not be entitled to cancel the contract in such cases unless these represent a significant change that makes the participation of the exhibitor in the event impossible or infructuous and Messe Muenchen India is unable to provide a like-for-like replacement to the exhibitor. In such cases, the exhibitor may cancel the contract and seek refund of the refundable portion of the participation fees. The exhibitor acknowledges that Messe Muenchen India prepares the venue and makes arrangements for the event well in advance in accordance with the booking made by the exhibitor which involves considerable upfront expenses on part of Messe Muenchen India. Therefore, in no circumstances other than the case covered above, the exhibitor is entitled to withdraw or cancel the contract after booking and if the exhibitor does so, Messe

Muenchen India shall be entitled to retain the participation fees as indicated below. Messe Muenchen India in such cases shall also be free to provide the space booked by the exhibitor to another exhibitor and this shall not affect Messe Muenchen India's right to claim the full participation fees paid / payable by the exhibitor.

Messe Muenchen India is entitled to withdraw or to terminate the contract if the exhibitor fails to meet his financial obligations to Messe Muenchen India on time. Messe Muenchen India has the right but not the obligation to extend the deadline by five (5) days if the deadline for payment has not been met. Messe Muenchen India is also entitled to withdraw or to terminate the contract if the exhibitor neglects his duty arising from this contract to respect Messe Muenchen India's rights, objects of legal protection and interests and Messe Muenchen India can no longer reasonably be expected to adhere to the contract or if the exhibitor fails to comply with rules and regulations as required for his performance of the contract under this document.

In the aforementioned cases Messe Muenchen India is entitled not only to withdraw or to terminate the contract but also to demand from the exhibitor the agreed participation fee as flat-rate compensation. Following issued acknowledgement, a compensation shall be charged when the exhibitors withdraws from the contract:

Earlier than 8 weeks before the show – 40% of the participation fees

Within 8 weeks before the show – 60% of the participation fees
Within 4 weeks before the show – 100% of the participation fees
Within 4 weeks before the show – 100% of the participation fees
An exhibitor will be entitled to a right of withdrawal of the Exhibitor Agreement in cases where statutory or regulatory provisions are in place according to which at any given point in time within a period of six weeks prior to the first day of the Show, no one will be allowed to exit from the country or part of the country where such Exhibitor has its domicile, or to enter in India; or that anyone entering in India from the country or part of the country where such Exhibitor has its domicile, shall place herself/himself under quarantine immediately upon entry.

#### A 6. Force maieure, cancellation of the event

If Messe Muenchen India is compelled, as a result of force majeure or other circumstances beyond its control (e.g., failure of the power supply), to vacate one or more exhibition areas, temporarily or for longer periods, or to postpone or curtail the trade fair, the exhibitors do not thereby acquire the right to withdraw or cancel, nor do they have any other claims against Messe Muenchen India, in particular claims for damages. If Messe Muenchen India cancels the event because it cannot hold the event as a result of force majeure or other circumstances beyond its control, or because it has become unreasonable for Messe Muenchen India to hold the event, Messe Muenchen India is not liable for damages and disadvantages to exhibitors arising from the cancellation of the event.

The participation fees are calculated in accordance with the rates specified in the Special Terms of

The participation fees are calculated in accordance with the rates specified in the Special Terms of Participation B (see part B "Participation fees"). Each square meter or part thereof will be included in full in the calculation, the floor area always being considered rectangular, without taking account of projections, supports, service connections and the like.

The applicant shall be invoiced for 100 % of the projected participation price shortly after receiving his written admission confirmation. This payment will be refunded if the applicant is not admitted to the trade fair but will be forfeited if unilaterally the applicant withdraws totally from the undertaking. Payment of the invoices is due immediately unless other payment deadlines are stated in the invoices. Payment of the participation price as well as payment for admitting co-exhibitors is a prerequisite for occupation of the exhibition area.

If exhibitors have ordered Messe Muenchen India services, Messe Muenchen India is entitled to withhold such services, including the supply of electricity, water, compressed air, etc., until the to obligations arising from previous events. Terms and conditions of payment are in accordance with the Special Terms of Participation B (see part B "Terms of payment"). Messe Muenchen India reserves the right to enforce the lessor's lien, as permitted by law, in order to secure Messe Muenchen India's claims arising from the rental. The exhibitor must inform Messe Muenchen India at any time about the ownership of articles, which are exhibited or to be exhibited. If an exhibitor does not meet his financial obligations, Messe Muenchen India can detain the exhibits and stand fittings and, at the exhibitor's expense, sell them at public auction or privately. The legal provisions on the realization of the pledge are—as far as permitted by law-excluded. Messe Muenchen India does not accept liability for damage to exhibits and stand fittings detained under this clause, unless Messe Muenchen India is guilty of intent gross negligence.

Upon special application by the exhibitor, the participation price and/or the payment for the admittance of co-exhibitors can be invoiced to a third party. As prerequisites, the third party must declare acceptance of the obligation or promise to pay the amount owed to Messe Muenchen India, and Messe Muenchen India must declare its agreement with such.

Should the exhibitor wish to have an invoice rewritten because the name, legal form or address of the recipient of the invoice has changed, the exhibitor is obliged to pay the organizer a sum amounting to EUR 50/INR 4,000 for each change of invoice unless the details in respect of name, legal form or address of the recipient of the invoice were incorrect on the original invoice and the organizer was responsible for the incorrect details. The exhibitors should be ultimately responsible for failure of third party.

Complaints about any defects in the stand or exhibition area are to be made in writing to Messe Muenchen India immediately on occupying the exhibition area, and at the latest on the last day for stand assembly, so that Messe Muenchen India can remedy such defects. Later complaints cannot be considered and cannot give rise to claims against Messe Muenchen India.

#### A 9. Liability and insurance

Messe Muenchen India is liable for personal injury (damage arising from injury to life, body or health) caused by neglect of duty for which Messe Muenchen India, its legal representatives or employees are responsible. Messe Muenchen India is also liable for any damage caused by grave breach of cardinal duties by Messe Muenchen India, its legal representatives or employees. In these cases, Messe Muenchen India is liable only if the damage is direct damage and not consequential damage and then only up to five (5) times the net participation fee, at most, INR 100,000 per claim. This limitation of liability applies only to entrepreneurs, legal persons under public law or special fund under public law. If the exhibitors are entrepreneurs, legal persons under public law or special funds under public law, for the avoidance of doubt, it is clarified that Messe Muenchen India is under no circumstances liable for damage to or loss of goods brought to the trade fair by the exhibitor or the stand fittings or furnishings. In this case, it is immaterial whether such damage or loss occurs before, during or after the trade fair.

The same applies to vehicles left on the trade fair grounds by exhibitors, their employees or representatives

For his part, the exhibitor is liable for any culpable damage to persons or property caused by him, his employees, representatives and exhibitors and their exhibition articles or exhibition installations and equipment. Each exhibitor is obligated to take out suitable insurance with sufficient insurance coverage with an insurer registered in the Republic of India and to pay the premiums incurred (including insurance tax) in good time.

#### A 10. Photography, filming, video recording and sketching

Only persons authorized by Messe Muenchen India and in possession of a valid Messe Muenchen India pass may film, photograph, or make sketches or video recordings in the exhibition halls and the outdoor exhibition area. Under no circumstances may photographic or other images or recordings be made of other exhibitors' stands. If this rule is infringed, Messe Muenchen India can demand that the recorded material be surrendered and take legal steps to achieve this end. Photographs of stands which are to be taken outside normal opening hours and need special lighting require Messe Muenchen India's prior consent. Such photographs require the main ring circuit to be switched on by the hall electrician. The exhibitor will be charged the costs incurred, insofar as they are not borne by the photographer. Messe Muenchen India is entitled to have photographs, drawings, films and video recordings made of events at the trade fair, of stands and exhibits, and to use them for advertising or general press publications.

#### A11. Catering, deliveries to stands

Only companies approved for the event grounds may supply exhibition stands with food, beverages and/or flowers. Deliveries to exhibition stands are only permitted with restrictions. Messe Muenchen India is authorized to allow deliveries to stands only at certain times.

#### A 12. Intellectual property rights

Messe Muenchen India expects exhibitors to respect the intellectual property rights of other exhibitors. For this end, Messe Muenchen India is entitled but not obliged to set up an Intellectual Property Complaint Office (IP Office) for each trade fair, whose purpose shall be to support exhibitors in cases of infringement of their IP rights by other exhibitors. If it is proved to Messe Muenchen India, by presentation of a court decision, that an exhibitor has infringed the intellectual property rights of another exhibitor with the articles on display, printed papers, advertising materials, or otherwise, then Messe Muenchen India is entitled, although not obliged, to remove from the offender's stand the exhibits, printed matter, or advertising material causing such infringement and to impound them until the end of the trade fair, to close the offender's stand, and/or to expel him and his staff from the trade fair grounds. Messe Muenchen India is also entitled to exclude the offender from future trade fairs. If such measures prove unjustified, no claim for damages can be made against Messe Muenchen India, unless the latter is guilty of gross negligence or wrongful intent. Without Prejudice to the generality of clause A24, the exhibitor agrees to indemnify and keep indemnified Messe Muenchen India from and against any action, liability, penalty, prosecution, cost charges, expenses, damages or claim of whatsoever nature arising from or resulting from the infringement or violation of the Intellectual Property Rights of any third party/other exhibitor by the exhibitor.

#### A 13. Exhibitors' passes

For the time in which the trade fair is held, the exhibitor receives a number of free exhibitors' passes as specified in the Special Terms of Participation. Any additional exhibitors' passes requested are charged for. All exhibitors' passes are numbered, and the passes are not transferable. Exhibitors' passes must not be given away or sold to unauthorized third parties, e.g., to persons or companies who wish to offer goods for sale or to render services at the trade fair center without corresponding authorization from Messe Muenchen India. Exhibitors' passes are issued only after payment of the participation fee, and the remuneration for the admission of any co- exhibitors.

#### A 14. Assembly, staffing and dismantling of stand

The dates for assembly and dismantling, specified in the Special Terms of Participation B, must be observed. Stands not occupied by the last day for assembly may be disposed of as Messe Muenchen India sees fit. Exhibitors admitted to the fair undertake to participate in the event. The stand must be properly equipped and staffed by qualified personnel throughout the trade fair during the prescribed opening hours. Particular attention should be paid to ensuring that the stand is already fully staffed when the trade fair opens. Exhibitors are not permitted to remove trade fair goods or dismantle their stands before the trade fair closes. If they break this rule, Messe Muenchen India is entitled to demand a penalty of EUR 350/INR 28,000.

Messe Muenchen India is entitled to exclude from future trade fairs any exhibitor whose stand is staffed by insufficiently qualified personnel during the trade fair's opening hours, who exhibits an incomplete range of goods or goods not admitted to the trade fair, who vacates or clears his stand before the end of the trade fair, or who otherwise infringes the Terms of Participation, without prejudice to Messe Muenchen India's right to cancel the contract in accordance with section A5 or to a claim for all costs thereby incurred by Messe Muenchen India.

Due to the ongoing COVID-19 pandemic situation, Messe Muenchen India is obliged to follow certain Standard Operating Procedures (SOPs) as stipulated by the Government of India from time to time with respect to organization of events/ exhibitions/public gatherings, etc. Therefore, Messe Muenchen India and the exhibitors are required to abide by the same and follow such SOPs Messe Muenchen India shall not be responsible for any loss/expenses incurred by following such norms, as required by the Government of India. Messe Muenchen India may or may not be able to inform the exhibitors of all such SOPs and it is the duty of the exhibitors to keep themselves updated of any relevant applicable SOPs and abide by them.

#### A 15. Verbal agreements

All verbal agreements, individual and special arrangements are valid only with Messe Muenchen India's written confirmation.

#### A 16. Regulations for use

Exhibitors must comply strictly with the building and use rules for the event grounds. Exhibitors are not permitted to spend the night in the halls or on the open-air grounds. Exhibitors must take the other participants in the event into consideration, must not act contrary to public policy and must not misuse their participation in the event for ideological, political or other purposes which have nothing to do with the

#### A 17. Period of limitation, period of exclusion

All the exhibitor's claims against Messe Muenchen India arising from the stand rental, and all legal proceedings in connection therewith lapse after a period of six months, unless permitted by applicable laws. This period of limitation starts at the end of the month in which the closing date of the fair falls. Notwithstanding the provisions set out in clause A8, any complaints about invoices are to be made in writing within a period of exclusion amounting to 14 days following receipt of the invoice concerned.

#### A 18. Place of performance, applicable law

Bengaluru shall be the place of performance for all financial obligations. Only the law of the Republic of India shall apply. This applies even in case of termination or withdrawal of any contractual relationship.

#### A 19. Jurisdiction, arbitration agreement

The following shall apply where the exhibitor is incorporated in the Republic of India:

In the event of any dispute, controversy or claim (collectively, "dispute") arising out of or relating to this rental contract, or the breach, termination or invalidity of this rental contract, both parties shall attempt in the first instance to resolve such dispute through friendly consultations. If any dispute is not resolved by friendly consultations, then the parties submit to the exclusive jurisdiction of courts and tribunals of competent jurisdiction in Mumbai.

The following shall apply where the exhibitor is incorporated or with their principal place of business outside the Republic of India:

Any dispute, controversy, claim or disagreement of any kind whatsoever between or among the parties in connection with or arising out of this agreement or the breach, termination or invalidity thereof (hereinafter referred to as a "dispute") shall be referred to and finally settled by arbitration. The arbitration shall be conducted in Mumbai in accordance with the Rules of Arbitration of the Indian Council "IMC" (the "rules"), which, as modified from time to time, are deemed to be incorporated by reference into this section (provided that, in the event of any conflict between the rules and the provisions of this clause, the latter shall prevail).

All arbitration proceedings shall be conducted in the English language. The arbitration shall be conducted by a panel of three (3) arbitrators consisting of one (1) arbitrator appointed by Messe Muenchen India, one (1) arbitrator appointed by the exhibitor and the third arbitrator appointed by the arbitrator shall be in Mumbai. The award rendered by the arbitrators shall be in writing and shall not make such decisions based on the principle of ex aequo et bono or as amiable compositor. The arbitrators shall set out the reasons for their decision. The award shall allocate or apportion the costs of the arbitration as the arbitrators deem fair. The parties agree that the arbitration award shall be final and binding on the parties. This applies even in case of termination or withdrawal of any contractual relationship.

In India, subject to the provisions of arbitration above, (A) with respect to any challenge, direct or indirect, to the arbitration ("Proceedings"), and (B) for the purpose of enforcement of the arbitral award, the courts and tribunals of competent jurisdiction at Mumbai shall have exclusive jurisdiction.

#### A 20. Data protection

In compliance with data protection legislation, the person-related data of the exhibitor is processed and used for fulfilling the business purposes of Messe Muenchen India and shared with third parties in order to fulfill the purposes of the contract.

Personal data of the exhibitor shall be used by third parties for marketing purposes of related trade fairs by the associate companies of Messe Muenchen India.

#### A 21. Severability clause

Should the provisions set out in the Terms of Participation or Technical Guidelines be or become legally invalid or incomplete, the validity of the other provisions or the contract concerned remains unaffected. In such a case, the contracting parties undertake to replace the invalid provision and/or fill the gap with a provision with which the contracting parties are most likely to achieve the economic purpose they pursue.

#### A 22. Authority

The exhibitor warrants that it has full power and capacity and authority to sign the "Exhibitor The exhibitor warrants that it has full power and capacity and authority to sign the application form.

#### A 23. Legal compliance

The exhibitor warrants that it follows the Indian laws at the time of signing the application form and shall always comply with Indian laws while performing its activity while participating in an event. The exhibitor is not restricted by any judgement, injunction, order, decree or award from signing the application form and performing activities under this event.

#### A 24. Indemnification

The exhibitor agrees to indemnify and keep indemnified Messe Muenchen India, its employees and agents from and against any action, liability, penalty, prosecution, notices, fines, investigation, cost, charges, expenses, damages or claim of whatsoever nature arising out of or resulting from any act attributable to the exhibitor, co-exhibitor, its employees and agents, involving (a) any loss, damage, destruction or injury to any property whether real or personal of Messe Muenchen India, its employees and agents; (b) any breach of the covenants herein contained or wrongful representations and warranties made by exhibitor, co-exhibitor, its employees and agents (c) any willful misconduct or gross negligence in performing its obligations under this agreement.

As of January 2023